LC8220



# JPEG Still Color Image Compression/Decompression LSI

# Preliminaly

### **Overview**

The LC8220 JPEG LSI implements digital still image compression and decompression conforming to the JPEG (Joint Photographic Expert Group) standard. The LC8220 includes the baseline system of the ISO 10918 (JPEG) standard, and requires no external components to construct an application that performs JPEG compliant compression/decompression.

# **Features**

- Conforms to the ISO 10918-1 baseline system
- Four quantization tables and four Huffman tables (two for AC and two for DC) are built in.
- · Hardware support for JPEG marker codes
- Built-in bidirectional YUV RGB converter
- Many color component sampling ratios are supported. (e.g., YUV 4:1:1 and YMCK 1:1:1:1, etc.)
- Level shift function that can be defined for each component
- · Built-in dual buffers for reduced data transfer load
- Bus sizing function that allows direct connection to 8-, 16-, and 32-bit busses
- Endian control function
- Three independent data buses

# **Package Dimensions**

unit: mm

### 3153A-QFP160



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### **Block Diagram**

The LC8220 has three independent buses.



#### **Pin Assignment**



No. 4909-2/13

### **Pin Functions**

Pin No.	Symbol	I/O	Function
1	V <sub>SS</sub>		Ground
2	CTLCS	1	Control bus chip select*2
3	CTLRD	1	Control bus read request <sup>*3</sup>
4	CTLWR		Control bus write request*4
5	CTLRDY	0	Control bus ready for read/write requests*5
6	CTLERR	0	Error interrupt request
7		0	Control bus interrupt request
8	CPUCTL	1	Connected CPU type setting for the control bus*1
9	CTLSIZE		Bus width selection for the control bus (0: 8 bits, 1: 16 bits)
10	V <sub>DD</sub>	<u> </u>	+5 V power supply
10	V <sub>SS</sub>	<u> </u>	Ground
12	CTLA7	1	
12	CTLA6	1	
13	CTLA5		
14	CTLA3		
15	CTLA4 CTLA3		Control address bus
16	CTLA3 CTLA2		
17	CTLA2 CTLA1		
18	CTLAT		
20	V <sub>DD</sub>		+5 V power supply
21	V <sub>SS</sub> CTLD15	—	Ground
22		1/0	
23	CTLD14	I/O	
24	CTLD13	I/O	
25	CTLD12	I/O	Control data bus (D15 to D8 are unused if an 8-bit CPU is used.*7)
26	CTLD11	I/O	
27	CTLD10	I/O	
28	CTLD9	I/O	
29	CTLD8	I/O	
30	V <sub>DD</sub>		+5 V power supply
31	V <sub>SS</sub>	-	Ground
32	CTLD7	I/O	
33	CTLD6	I/O	
34	CTLD5	I/O	
35	CTLD4	I/O	Control data bus
36	CTLD3	I/O	
37	CTLD2	I/O	
38	CTLD1	I/O	
39	CTLD0	I/O	
40	V <sub>DD</sub>	_	+5 V power supply
41	V <sub>SS</sub>		Ground
42	CLK		System clock
43	CLKSEL		Clock divisor selection (0: no divisor, 1: divisor used)*6
44	RESET		System reset
45	TEST		Test mode selection (0: normal operation, 1: test mode)*6
46	TESTOUT	0	Test result output*8
47	MDD10	I/O	
48	MDD9	I/O	Test mode data bus <sup>17</sup>
49	MDD8	I/O	
50	V <sub>DD</sub>		+5 V power supply
51	V <sub>SS</sub>		Ground
52	MDD7	I/O	
53	MDD6	I/O	Test mode data bus*7
54	MDD5	I/O	

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Pin No.	Symbol	I/O	Function
55	MDD4	1/0	
56	MDD3	1/0	1
57	MDD2	1/0	 Test mode data bus*7
58	MDD1	1/0	
59	MDD0	I/O	1
60	V <sub>DD</sub>		+5 V power supply
61	V <sub>SS</sub>	_	Ground
62	TESTI1	1	
63	TESTI2	1	
64	TESTI2	1	Test mode input pins <sup>*9</sup>
65	TESTI4		
66	TESTI5		
	TESTIS TESTO1	0	
67	TESTO2	0	Test mode output pins <sup>18</sup>
68			Test mede innut size
69	TESTI6		Test mode input pin <sup>eg</sup>
70	TESTO3	0	Test mode output pin <sup>18</sup>
71			Connected CPU type setting for the pixel bus*1
72	PXCS		Pixel bus chip select*2
73	PXRD		Pixel bus read request*3
74	PXWR		Pixel bus write request*4
75	PXRDY	0	Pixel bus ready for read/write requests*5
76	PXINT	0	Pixel bus interrupt request
77	PXRLS		Pixel bus interrupt release
78	PXEND	0	Pixel bus last data output indicator
79	(NC)	_	
80	V <sub>DD</sub>	_	+5 V power supply
81	V <sub>SS</sub>	_	Ground
82	PXD31	I/O	
83	PXD30	I/O	
84	PXD29	I/O	
85	PXD28	I/O	Pixel data bus
86	PXD27	I/O	(D31 to D16 are unused if a 16-bit CPU is used and D31 to D8 are unused if an 8-bit CPU is used.*7)
87	PXD26	I/O	
88	PXD25	I/O	
89	PXD24	I/O	
90	V <sub>DD</sub>	-	+5 V power supply
91	V <sub>SS</sub>	_	Ground
92	PXD23	I/O	
93	PXD22	I/O	
94	PXD21	I/O	
95	PXD20	I/O	Pixel data bus
96	PXD19	I/O	(D31 to D16 are unused if a 16-bit CPU is used and D31 to D8 are unused if an 8-bit CPU is used.*7)
97	PXD18	I/O	
98	PXD17	I/O	
99	PXD16	I/O	
100	V <sub>DD</sub>	_	+5 V power supply
101	V <sub>SS</sub>	_	Ground
102	PXD15	I/O	
103	PXD14	I/O	
104	PXD13	I/O	
105	PXD12	I/O	Pixel data bus
106	PXD11	I/O	(D31 to D16 are unused if a 16-bit CPU is used and D31 to D8 are unused if an 8-bit CPU is used.*7)
107	PXD10	I/O	
108	PXD9	I/O	1
109	PXD8	I/O	1
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I/O	Function
—	+5 V power supply
_	Ground
I/O	
I/O	-
I/O	-
I/O	Pixel data bus
I/O	
I/O	-
I/O	-
I/O	-
	+5 V power supply
_	Ground
1	Bus width selection for the pixel bus
1	(PXSIZE [1,0] = 00: 8 bits, 01: 16 bits, 1*: 32 bits)
1	Code bus chip select*2
	Code bus read request*3
	Code bus vrite request*4
0	Code bus ready for read/write requests*5
0	Code bus interrupt request
1	Code bus interrupt release
0	Code bus last data output
1	Code bus forcible buffer flush
	-
	_
	_
	_
1	Connected CPU type setting for the code bus*1
1	Bus width setting for the code bus (0: 8 bits, 1: 16 bits)
	+5 V power supply
_	Ground
I/O	
I/O	
I/O	
I/O	Code data bus (D15 to D8 are unused if an 8-bit CPU is used.*7)
I/O	
I/O	
I/O	
I/O	
—	+5 V power supply
—	Ground
I/O	
I/O	
I/O	
I/O	Code data bue
I/O	- Code data bus
I/O	1
I/O	1
I/O	1
_	+5 V power supply
ems a	I/O

Note 1, 2, 3, 4, 5: These items are related to the CPU type. ound).

6:	Connect to	V <sub>SS</sub>	(gro

Must be pulled up. These are NC pins. Connect to V<sub>DD</sub>. 0: 7: 8: 9:

	Z**CS <sup>2</sup>	Z**RD3	Z**WR4	Z**RDY5
8086 family CPU (CPU = 1)	CS	RD	WR	RDY
68000 family CPU (CPU = 0)	AS	R/W	DS	ACK

# **Specifications**

# Absolute Maximum Ratings at $Ta = 25^{\circ}C$ , GND = 0 V

Parameter	Symbol	Conditions	Ratings	Unit
Maximum supply voltage	V <sub>DD</sub> max		-0.3 to +7.0	V
I/O voltages	V <sub>I</sub> , V <sub>O</sub>		–0.3 to V <sub>DD</sub> + 0.3	V
Operating temperature	Topr		-30 to +70	°C
Storage temperature	Tstg		-55 to +125	°C
Soldoring tomporature		Hand soldering: 3 seconds	350	°C
Soldering temperature		Reflow soldering: 10 seconds	235	°C

### Allowable Operating Ranges at Ta = -30 to $+70^{\circ}C$ , GND = 0 V

Parameter	Symbol	Conditions	min	typ	max	Unit
Supply voltage	V <sub>DD</sub>		4.5		5.5	V
Input voltage	V <sub>IN</sub>		0		V <sub>DD</sub>	V

## DC Characteristics at Ta = -30 to +70°C, $V_{DD}$ = 4.5 to 5.5 V, GND = 0 V

Parameter	Symbol	Conditions	min	typ	max	Unit
Input high level voltage	VIH	TTL compatible: CTLCS, CTLRD, CTLWR, CPUCTL, CTLSIZE, CTLA7 to CTLA0, CLKSEL, RESET, TEST, CTLD15 to CTLD0	2.2			V
Input low level voltage	VIL	TTL compatible: CPUPX, PXCS, PXRD, PXWR, PXD31 to PXD0, PXRLS, PXSIZE0			0.8	V
Input leakage current	IL.	PXSIZE1, CDCS, CDRD, CDWR, CDRLS, CDFLSH, CPUCD, CDSIZE, CDD15 to CDD0	-10		+10	μΑ
Output high level voltage	V <sub>OH</sub>	$\label{eq:comparameters} \begin{array}{l} I_{OH} = -3 \text{ mA, TTL compatible: } \overline{\text{CTLRDY}}, \overline{\text{CTLERR}}, \\ \overline{\text{CTLINT}}, \overline{\text{TESTOUT}}, \overline{\text{CTLD15}} \text{ to } \overline{\text{CTLD0}}, \overline{\text{PXRDY}}, \\ \overline{\text{PXINT}}, \overline{\text{PXEND}}, \overline{\text{PXD31}} \text{ to } \overline{\text{PXD0}}, \overline{\text{CDRDY}}, \overline{\text{CDINT}}, \\ \overline{\text{CDEND}}, \overline{\text{CDD15}} \text{ to } \overline{\text{CDD0}} \end{array}$	V <sub>DD</sub> – 2.1			V
Output low level voltage	V <sub>OL</sub>	$\label{eq:comparameters} \begin{array}{l} I_{OH} = -3 \\ \hline CTLINT, \ TESTOUT, \ CTLD15 \ to \ CTLD0, \ \overrightarrow{PXRDY}, \\ \hline PXINT, \ \overrightarrow{PXEND}, \ PXD31 \ to \ PXD0, \ \overrightarrow{CDRDY}, \ \overrightarrow{CDINT}, \\ \hline \overrightarrow{CDEND}, \ CDD15 \ to \ CDD0 \end{array}$			0.4	V
Output leakage current	I <sub>OZ</sub>	For high impedance outputs: CTLD15 to CTLD0, PXD31 to PXD0, CDD15 to CDD0	-10		+10	μA
Oscillator frequency	fosc	CLK			16.67	MHz
Current drain	I <sub>DD</sub>	V <sub>DD</sub> = 5.0 V		145		mA

#### **AC Characteristics**

Code Bus Interface Timing

Code Bus Read Cycle



Code Bus Read Cycle (type 1)





	Item	Minimum	Maximum	Unit
t1	Read signal assert setup time (referenced to CLK)	8		ns
t2	Read signal assert hold time (referenced to CLK)	15		ns
t3	Chip select stabilization time (referenced to the read signal)	0		ns
t4	Chip select hold time (referenced to the read signal)	0		ns
t5	Ready signal response delay time (referenced to the read signal)		T + t1 + 20	ns
t6	Ready signal release delay time (referenced to the read signal)		t7 + 27	ns
t7	Read signal negate setup time (referenced to CLK)	8		ns
t8	Read signal negate hold time (referenced to CLK)	15		ns
t9	Data output delay time (referenced to the ready signal)		15	ns
t10	Data output hold time (referenced to the read signal)		t7 + 15	ns
Т	Clock period	60		ns

Code Bus Write Cycle



Code Bus Write Cycle (type 1)





	Item	Minimum	Maximum	Unit
t1	Write signal assert setup time (referenced to CLK)	8		ns
t2	Write signal assert hold time (referenced to CLK)	15		ns
t3	Chip select stabilization time (referenced to the write signal)	0		ns
t4	Chip select hold time (referenced to the write signal)	0		ns
t5	Write cycle selection signal stabilization time (referenced to the write signal)	0		ns
t6	Write cycle selection signal hold time (referenced to the write signal)	0		ns
t7	Ready signal response delay time (referenced to the write signal)		T + t1 + 20	ns
t8	Ready signal release delay time (referenced to the write signal)		t9 + 27	ns
t9	Write signal negate setup time (referenced to CLK)	8		ns
t10	Write signal negate hold time (referenced to CLK)	15		ns
t11	Data setup time (referenced to the ready signal)	45		ns
t12	Data hold time (referenced to the ready signal)	15		ns
Т	Clock period	60		ns

Pixel Bus Interface Timing

Pixel Bus Read Cycle



Pixel Bus Read Cycle (type 1)





	Item	Minimum	Maximum	Unit
t1	Read signal assert setup time (referenced to CLK)	8		ns
t2	Read signal assert hold time (referenced to CLK)	15		ns
t3	Chip select stabilization time (referenced to the read signal)	5		ns
t4	Chip select hold time (referenced to the read signal)	5		ns
t5	Ready signal response delay time (referenced to the read signal)		T + t1 + 20	ns
t6	Ready signal release delay time (referenced to the read signal)		t7 + 28	ns
t7	Read signal negate setup time (referenced to CLK)	8		ns
t8	Read signal negate hold time (referenced to CLK)	15		ns
t9	Data output delay time (referenced to the ready signal)		15	ns
t10	Data output hold time (referenced to the read signal)		t7 + 18	ns
Т	Clock period	60		ns

Pixel Bus Write Cycle



Pixel Bus Write Cycle (type 1)





	Item	Minimum	Maximum	Unit
t1	Write signal assert setup time (referenced to CLK)	8		ns
t2	Write signal assert hold time (referenced to CLK)	15		ns
t3	Chip select stabilization time (referenced to the write signal)	5		ns
t4	Chip select hold time (referenced to the write signal)	5		ns
t5	Write cycle selection signal stabilization time (referenced to the write signal)	5		ns
t6	Write cycle selection signal hold time (referenced to the write signal)	5		ns
t7	Ready signal response delay time (referenced to the write signal)		T + t1 + 20	ns
t8	Ready signal release delay time (referenced to the write signal)		t9 + 28	ns
t9	Write signal negate setup time (referenced to CLK)	8		ns
t10	Write signal negate hold time (referenced to CLK)	15		ns
t11	Data setup time (referenced to the ready signal)	60		ns
t12	Data hold time (referenced to the ready signal)	20		ns
Т	Clock period	60		ns

Control Bus Interface Timing

#### Control Bus Read Cycle



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### Control Bus Register Read Cycle (type 1)



### Control Bus Register Read Cycle (type 2)

	Item	Minimum	Maximum	Unit
t1	Read signal assert setup time (referenced to CLK)	10		ns
t2	Read signal assert hold time (referenced to CLK)	15		ns
t3	Chip select stabilization time (referenced to the read signal)	10		ns
t4	Chip select hold time (referenced to the read signal)	15		ns
t5	Address stabilization time (referenced to the read signal)	0		ns
t6	Address hold time (referenced to the read signal)	5		ns
t7	Ready signal response delay time (referenced to the read signal)		T + t1 + 24	ns
t8	Ready signal release delay time (referenced to the read signal)		t9 + 30	ns
t9	Read signal negate setup time (referenced to CLK)	12		ns
t10	Read signal negate hold time (referenced to CLK)	15		ns
t11	Data output delay time (referenced to the ready signal)		0	ns
t12	Data output hold time (referenced to the read signal)		t9 + 30	ns
Т	Clock period	60		ns

Control Bus Write Cycle



## Control Bus Register Write Cycle (type 1)



Control Bus Register Write Cycle (type 2)

	Item	Minimum	Maximum	Unit
t1	Write signal assert setup time (referenced to CLK)	12		ns
t2	Write signal assert hold time (referenced to CLK)	15		ns
t3	Chip select stabilization time (referenced to the write signal)	10		ns
t4	Chip select hold time (referenced to the write signal)	15		ns
t5	Write cycle selection signal stabilization time (referenced to the write signal)	10		ns
t6	Write cycle selection signal hold time (referenced to the write signal)	10		ns
t7	Address stabilization time (referenced to the write signal)	0		ns
t8	Address hold time (referenced to the write signal)	5		ns
t9	Ready signal response delay time (referenced to the write signal)		T + t1 + 24	ns
t10	Ready signal release delay time (referenced to the write signal)		t11 + 32	ns
t11	Write signal negate setup time (referenced to CLK)	5		ns
t12	Write signal negate hold time (referenced to CLK)	15		ns
t13	Data setup time (referenced to the ready signal)	60		ns
t14	Data hold time (referenced to the ready signal)	20		ns
Т	Clock period	60		ns

Hardware Reset Timing



#### Hardware Reset Timing

	ltem	Minimum	Maximum	Unit
t1	Reset signal pulse width	2T		ns
t2	LSI access disabled time	5T		ns
Т	Clock period	60		ns

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